RL-SQC-304 Rev 1.0

Printed Circuit Board Assembly (PCBA) Requirements – B

DOCUMENT PROPERTIES

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<th>Supplier Quality Clause (Doc Type) (see page 1)</th>
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DOCUMENT APPROVAL

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<tr>
<th>Author</th>
<th>Reviewer</th>
<th>Approver</th>
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<tr>
<td>l.webster</td>
<td>m.heneghan</td>
<td>a.bernardo</td>
<td>17 Nov, 2023</td>
<td>Released</td>
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| Group          | Electronics – General |
1. Printed Circuit Board Assembly (PCBA) Data Package
   b. All manufacturer reports/results.
      i. The following shall be provided if the PCB was produced or
         procured by the PCBA subcontractor.
         1. The PCBA manufacturer shall include the items listed
            below:
            a. Micro Sections
               i. Final micro-sections coupon analysis shall
                  be provided to Rocket Lab
               ii. Coupon design shall be in accordance to
                   IPC-2221 and the specified finished PCB
                   characteristics.
            b. If applicable, a complete list of the test results
               performed at the bare-board level or on the
               unpotted and potted harnesses.
            c. Results of ionic contamination testing
            d. All deviation and waiver reports, including all
               MRB actions taken on the PCBs or materials.
            e. All raw material reports and supplier
               certifications, if any
   c. The PCBA Data Package shall comprise the following document:
      i. As Built List (ABL)
         1. Part number and Lot or Date code Information for all
            components shall be recorded to the PCBA batch
      ii. Material certificates
         1. Material used shall be traceable to the manufacturer’s
            lot number through date code
      iii. List of Assembly Materials (solder, ink, wire, flux, etc.)
         1. Lot and expiration date records shall be kept and
            provided upon request of Rocket Lab
      iv. Deviations from drawings and parts lists and objective
          evidence for the approval
      v. Copies of all redlined drawings and parts lists
      vi. Evidence of approval from Rocket Lab for all non-
          conformances with disposition of Use As Is and/or Repair
      vii. Rework documentation shall be kept and provided upon
           request of Rocket Lab
      viii. Surface Mount Process Reflow Profile shall be kept and
           provided upon request of Rocket Lab
      ix. X-Ray Images of CGA, BGA and BTC components shall be
          kept and provided upon request of Rocket Lab
      x. High resolution photo documentation of all sides of the
         completed PCBA shall be kept and provided upon request of
         Rocket Lab
      xi. If required, documentation for PCB or Component bake out
      xii. Unless otherwise specified, Flying Probe Data shall be
           submitted as part of the PCBA Data Package

2. Handling and Packaging
   a. Handling shall be in compliance with the requirements documented
      in appendix B of IPC-A-610
1 Glossary

Glossary Term

No content found.

2 Revision History

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<td>1</td>
<td>@Logan Webster</td>
<td>14 Nov 2023</td>
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3 Document Properties

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